

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
COLLABRX, INC.	08/13/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD
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PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	6495449
Patent Number:	6670266
Patent Number:	7163721
Patent Number:	6919101
Patent Number:	6777331
Patent Number:	7087522
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NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R> McClure/
DATE SIGNED:	10/16/2014
Total Attachments: 3	

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PATENT ASSIGNMENT

This Patent Assignment (this "Assignment") is made effective this 13th day of August, 2013, by and between CollabRx Inc, a corporation organized and existing under the laws of the State of Delaware with principal offices located at 44 Montgomery Street, Suite 800, San Francisco, CA 94104 ("Assignor") and Taiwan Semiconductor Manufacturing Company Ltd., a company, organized and existing under the laws of the Republic of China with principal offices located at No. 8, Li-Hsin Road 6 Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77 ("Assignee").

WHEREAS, Assignor possesses certain rights in and to the patents and patent applications listed in Schedule A attached hereto and the invention(s) described and/or claimed in such patents and patent applications (collectively, the "Patent Rights"); and

WHEREAS, pursuant to that certain Patent Purchase Agreement between Assignor and Assignee, dated as of the date hereof (the "Purchase Agreement"), Assignor assigned to Assignee the Patent Rights.

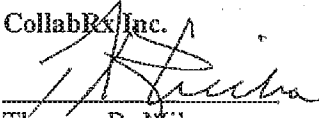
NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of the amounts paid to Assignee in the Purchase Agreement, and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignor has sold, assigned and transferred and by these presents does hereby sell, assign and transfer unto said Assignee, its successors, assigns, and legal representatives, Assignor's entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to the invention(s) described and/or claimed in said Patent Rights, together with Assignor's entire right, title and interest in and to the patents and patent applications listed in Schedule A and such other patents as may issue thereon or claim priority under United States law or international convention, including but not limited to non-provisionals, continuations, divisionals, reissues, reexaminations, extensions, and substitutions of said patents and patent applications or such other patents, and any right, title and interest Assignor may have in applications to which said Patent Rights claim priority; said invention(s), patent applications and patents to be held and enjoyed by said Assignee for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said patents may be granted as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made; Assignor hereby conveys all of its rights arising under or pursuant to any and all United States laws and international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for patent, including but not limited to any cause(s) of action and damages accruing prior to this assignment. Assignor hereby acknowledges that this assignment, being of Assignor's entire right, title and interest in and to said invention(s), applications and patents carries with it the right in Assignee to apply for and obtain from competent authorities in all countries of the world any and all patents by attorneys and agents of Assignee's selection and the right to procure the grant of all patents to Assignee in its own name as assignee of Assignor's entire right, title and interest therein;

AND, Assignor does hereby authorize and request the Director of the United States Patent and Trademark Office and the empowered officials of all other governments to issue such Patent Rights or patents as shall be granted upon said Patent Rights, or applications based thereon, to said Assignee, its successors, assigns, or legal representatives.

Assignee and Assignor also agree that multiple copies of this Assignment may be executed, each of which shall be deemed an original, and each of which shall be valid and binding upon Assignee and Assignor.

Assignee shall bear all responsibility and expense for preparing any instrument of assignment or transfer from Assignor to Assignee and for recording the same, any fee or tax levied thereon, and all prosecution and maintenance costs incurred with respect to the Patents.

IN WITNESS WHEREOF, Assignor and Assignee have caused this Assignment to be executed by their duly authorized officers as of the date first written above.

Assignor: CollabRx Inc.
By: 
Name: Thomas R. Mika
Title: President and Chief Executive Officer

Assignee: Taiwan Semiconductor
Manufacturing Company Ltd.
Name: Richard Thurston
Signature: _____
Title: Senior Vice President and General
Counsel

SCHEDULE A

PATENT RIGHTS

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
6495449	US	03/07/2000	Multilayered diffusion barrier structure for improving adhesion property Tue Nguyen
6670266	US	11/13/2002	Multilayered diffusion barrier structure for improving adhesion property Tue Nguyen
7163721	US	02/04/2003	Method to plasma deposit on organic polymer dielectric film Zhihong Zhang
6919101	US	02/04/2003	Method to deposit an impermeable film on porous low-k dielectric film Zhihong Zhang
<u>09/519,965</u>	<u>US</u>	<u>03/07/2000</u>	<u>Multilayered copper structure for improving adhesion property</u> <u>Tue Nguyen</u>
6777331	US	08/23/2002	Multilayered copper structure for improving adhesion property Tue Nguyen
7087522	US	03/08/2004	Multilayer copper structure for improving adhesion property Tue Nguyen

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RECORDED: 10/16/2014

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